



Customer Information Notification

201808016I

Issue Date: 30-Nov-2018

Effective Date: 01-Dec-2018

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#).



Management Summary

Assembly transfer to ASE-Chungli Taiwan assembly site requires pin 1 indicator change for the following products: MMA845x family, SX845x family, FXLS8471, FXOS8700, MM8491 and FXLN83xx family.

Change Category

- | | | | | |
|--|-----------------------------------|---|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly | <input type="checkbox"/> Mechanical Materials Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly | <input type="checkbox"/> Location Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

MMA845x, SX845x,
FXLS8471,
FXOS8700,
MMA8491 &
FXLN83xx Pin 1
Indicator Change

Description

NXP Semiconductors announces the change of the pin 1 indicator for the following products; MMA845x family, SX845x family, FXLS8471, FXOS8700, MM8491 and FXLN83xx family. This change will modify the pin 1 diameter from 0.26mm to 0.40mm +/- 0.10mm and will modify the pin 1 placement from 0.11mm to 0.25mm +/- 0.10mm vertically from the date code line. See attachment for visual example of the change.

Reason

Pin 1 indicator has been changed to be more visible and to accommodate internal NXP vision systems.

Identification of Affected Products

Top side marking

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Additional documents: [view online](#)



Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Michelle Kelsey
Position Product Line Manager
e-mail address michelle.kelsey@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.